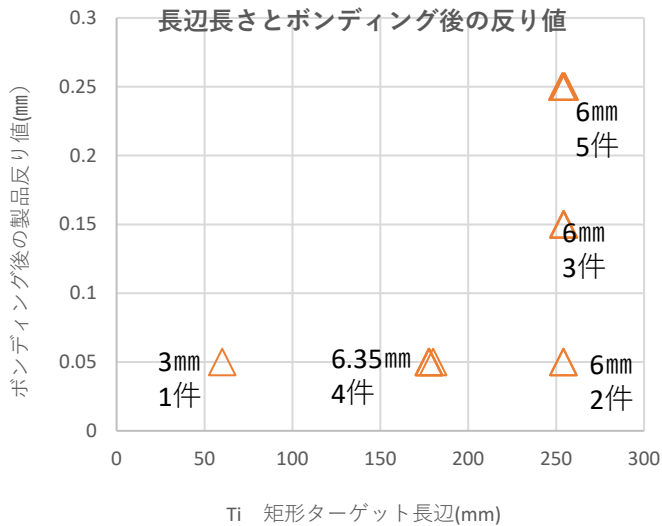
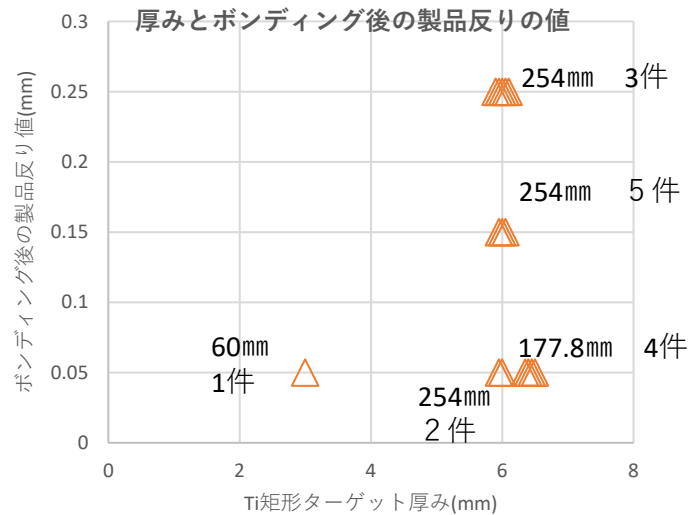


We offer bonding processing of sputtering target (planer and cylindrical). We will continue the discussions with our customers for the detailed evaluation results of our Bonding process as shown below.

Ti矩形ターゲット :



Ti矩形ターゲット :



SiO₂円盤ターゲット

直径とボンディング後反りの関係

